

### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	30	V
Average Forward Current (See also figure 4)	I <sub>F(AV)</sub>	2.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	30	А

## **Thermal Characteristics**

Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance Junction to Soldering Point	$R_{ heta}$ JS	_	6.0	°C/W
Thermal Resistance Junction to Ambient Air (Note 5) T <sub>A</sub> = +25°C	$R_{ hetaJA}$	177	_	°C/W
Operating Temperature Range	$T_J$	-65 to +125		°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +150		°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

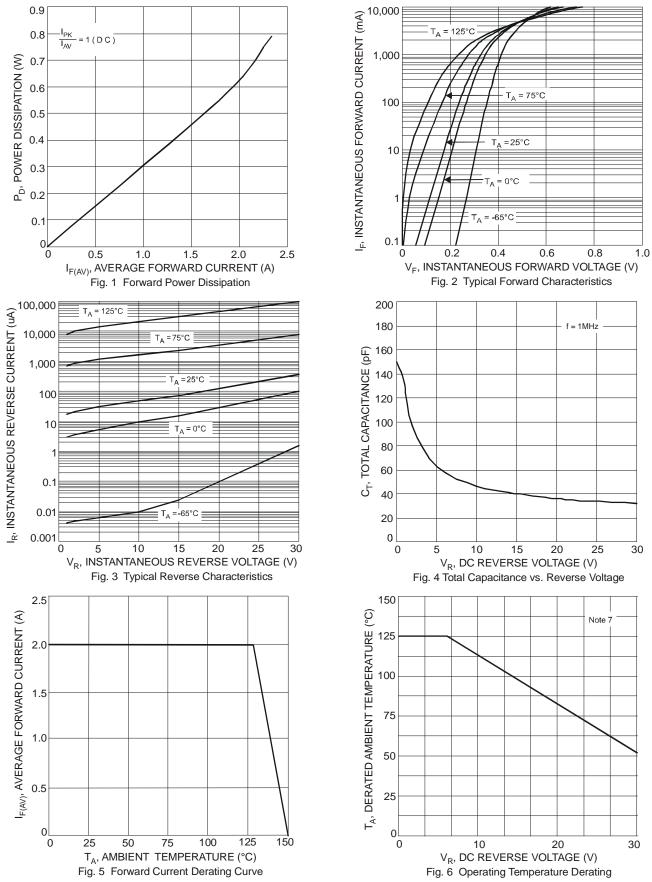
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	30		_	V	$I_R = 1.5 \text{mA}$
Forward Voltage	V <sub>F</sub>		0.37	0.45		I <sub>F</sub> = 2.0A, T <sub>A</sub> = +25°C
Forward voltage		_	0.30	0.36		$I_F = 2.0A, T_A = +125$ °C
Leakage Current (Note 6)	I <sub>R</sub>		40	250	μΑ	V <sub>R</sub> = 5V, T <sub>A</sub> = +25°C
		_	0.37	1.5	mA	$V_R = 30V, T_A = +25^{\circ}C$
Total Capacitance	C <sub>T</sub>		40	_	pF	V <sub>R</sub> = 10V, f = 1.0MHz

Notes:

<sup>5.</sup> FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com.

<sup>6.</sup> Short duration pulse test used to minimize self-heating effect.



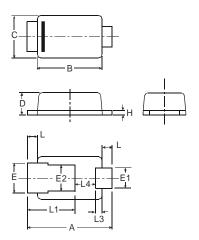


Notes: 7. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com.



# **Package Outline Dimensions**

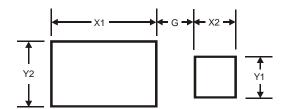
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



POWERDI <sup>®</sup> 323				
Dim	Min	Max	Тур	
Α	2.40	2.60	2.50	
В	1.85	1.95	1.90	
С	1.20	1.30	1.25	
D	0.60	0.70	0.65	
Е	0.78	0.98	0.88	
E1	0.50	0.70	0.60	
E2	0.60	1.00	0.80	
Н	0.08	0.18	0.13	
L	0.20	0.40	0.30	
L1			1.40	
L3		_	0.20	
L4	0.40	0.80	0.60	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.5
X1	2.0
X2	0.8
Y1	0.8
Y2	1.1



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